

22nd ACM/IEEE



www.SLIPonline.org

International Workshop on System-Level Interconnect Problems and Pathfinding (SLIP²)

Co-located with ACM/IEEE Intl. Conf. on Computer-Aided Design

November 5, 2020

San Diego, California, USA

Co-sponsored by ACM SIGDA and IEEE CEDA (pending)

Steering Committee Chair: Dirk Stroobandt (UGent)
General Chair: Andrew Kahng (UC San Diego)
Technical Program Co-Chairs: Shantanu Dutt (UIC), Rasit Topaloglu (IBM)
Special Sessions Co-Chairs: Ismail Bustany (Xilinx), Payman Zarkesh-Ha (U. New Mexico)
Finance Chair: Baris Taskin (Drexel)
Publicity Chair: Poona Bahrebar (UC Irvine and UGent)
Publications Chair: Seungwon Kim (UC San Diego)

Steering Committee Members:
Chung-Kuan Cheng
Brian Cline
Tsung-Yi Ho
Selcuk Kose
Baris Taskin

The technical goal of the workshop is to (1) identify fundamental problems, and (2) foster new pathfinding of design, analysis, and optimization of interconnect and communication fabrics in electronic systems. **Special emphases this year are predictive system interconnect modeling technologies, and novel interconnect technologies and architectures for a beyond-Moore era.** Further, a more interactive, workshop-like tone and format - recalling earlier editions of the SLIP workshop - is a goal for SLIP² this year.

Technical topics include but are not limited to:

- Learning and predictive models for interconnect at various IC and system design stages
- Roadmapping and pathfinding of interconnect technology and architectures
- Roadmapping and pathfinding of chip-to-chip interconnect, chipllets, and chip-package interfaces
- System-level design for FPGAs, NoCs, reconfigurable systems

- 2.5D and 3D-integrated system interconnect optimization, projection and pathfinding
- Design, analysis, and (co)optimization of power and clock distribution networks
- Topologies and fabrics of multi- and many-core architectures
- Predictive models for power and performance of system-level interconnects
- Interconnects in social, genetic, and biological systems
- Interconnects in complex networks and high-performance computing
- Interconnects in quantum architectures
- System-level interconnect reliability, aging, thermal, yield and cost issues
- Bio-inspired connectionist systems, such as artificial neural networks

Format:

The workshop includes keynotes, regular paper sessions, interactive panels, tutorials, invited talks, and interactive poster sessions.

Keynote Talk:

To be determined.

Student Awards:

Student Awards may be available. Please check the website for more information.

Submission:

We invite authors to submit papers of 6 to 8 pages, double-columned, 9pt or 10pt font in ACM proceedings format available at <https://www.acm.org/publications/proceedings-template>

To permit double blind review, all papers must remove author information (submissions with author information will be rejected). Authors should submit papers electronically: <https://easychair.org/conferences/?conf=slip2>

Important Dates:

Abstract Registration: August 14, 2020

Paper Submission: August 21, 2020

Author Notification: September 14, 2020

Final Version Upload: October 2, 2020